NB2305A

3.3 V Zero Delay Clock Buffer

The NB2305A is a versatile, 3.3 V zero delay buffer designed to distribute high−speed clocks. It accepts one reference input and drives out five low−skew clocks. It is available in a 8 pin package.

The −1H version of the NB2305A operates at up to 133 MHz, and has higher drive than the −1 devices. All parts have on−chip PLL's that lock to an input clock on the REF pin. The PLL feedback is on−chip and is obtained from the CLKOUT pad.

Multiple NB2305A devices can accept the same input clock and distribute it. In this case the skew between the outputs of the two devices is guaranteed to be less than 700 ps.

All outputs have less than 200 ps of cycle−to−cycle jitter. The input and output propagation delay is guaranteed to be less than 350 ps, and the output to output skew is guaranteed to be less than 250 ps.

The NB2305A is available in two different configurations, as shown in the ordering information table. The NB2305A1 is the base part. The NB2305Ax1H* is the high drive version of the −1 and its rise and fall times are much faster than −1 part.

Features

- 15 MHz to 133 MHz Operating Range, Compatible with CPU and PCI Bus Frequencies
- Zero Input − Output Propagation Delay
- Multiple Low−Skew Outputs
- Output−Output Skew Less than 250 ps
- Device−Device Skew Less than 700 ps
- One Input Drives 5 Outputs
- Less than 200 ps Cycle−to−Cycle Jitter is Compatible with Pentium® Based Systems
- Available in 8 Pin, 150 mil SOIC Package and 8 Pin TSSOP 4.4 mm
- 3.3 V Operation, Advanced 0.35 μ CMOS Technology
- Industrial Temperature Range
- These are Pb−Free Devices

*x = I for Industrial.

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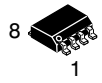
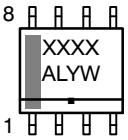
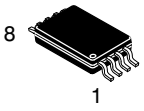
MARKING DIAGRAMS*

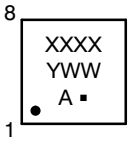


SOIC−8
D SUFFIX
CASE 751





TSSOP−8
DT SUFFIX
CASE 948S



XXXX	= Device Code
A	= Assembly Location
L	= Wafer Lot
Y	= Year
W	= Work Week
▪	= Pb−Free Package

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

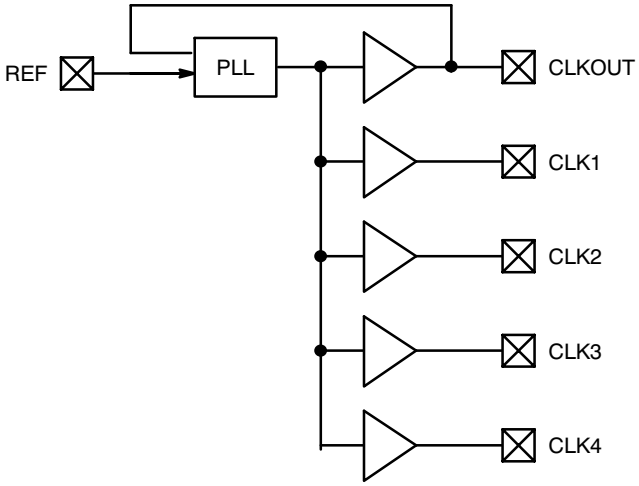


Figure 1. Block Diagram

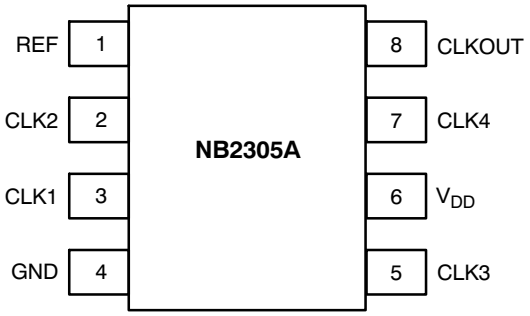


Figure 2. Pin Configuration

Table 1. PIN DESCRIPTION

Pin #	Pin Name	Description
1	REF (Note1)	Input reference frequency, 5 V tolerant input.
2	CLK2 (Note 2)	Buffered clock output.
3	CLK1 (Note 2)	Buffered clock output.
4	GND	Ground.
5	CLK3 (Note 2)	Buffered clock output.
6	V_{DD}	3.3 V supply.
7	CLK4 (Note 2)	Buffered clock output.
8	CLKOUT (Note 2)	Buffered clock output, internal feedback on this pin.

1. Weak pulldown.
2. Weak pulldown on all outputs.

Table 2. MAXIMUM RATINGS

Parameter	Min	Max	Unit
Supply Voltage to Ground Potential	−0.5	+7.0	V
DC Input Voltage (Except REF)	−0.5	V_{DD} + 0.5	V
DC Input Voltage (REF)	−0.5	7	V
Storage Temperature	−65	+150	°C
Maximum Soldering Temperature (10 sec)		260	°C
Junction Temperature		150	°C
Static Discharge Voltage (per MIL−STD−883, Method 3015)		>2000	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 3. OPERATING CONDITIONS FOR INDUSTRIAL TEMPERATURE DEVICES

Parameter	Description	Min	Max	Unit
V_{DD}	Supply Voltage	3.0	3.6	V
T_A	Operating Temperature (Ambient Temperature) Industrial	−40	85	°C
C_L	Load Capacitance, below 100 MHz		30	pF
C_L	Load Capacitance, from 100 MHz to 133 MHz		10	pF
C_{IN}	Input Capacitance		7	pF

Table 4. ELECTRICAL CHARACTERISTICS FOR INDUSTRIAL TEMPERATURE DEVICES

Parameter	Description	Test Conditions	Min	Max	Unit
V_{IL}	Input LOW Voltage (Note 3)			0.8	V
V_{IH}	Input HIGH Voltage (Note 3)		2.0		V
I_{IL}	Input LOW Current	V_{IN} = 0 V		50	μA
I_{IH}	Input HIGH Current	V_{IN} = V_{DD}		100	μA
V_{OL}	Output LOW Voltage	I_{OL} = 8 mA (−1) I_{OL} = 12 mA (−1H)		0.4	V
V_{OH}	Output HIGH Voltage	I_{OH} = −8 mA (−1) I_{OH} = −12 mA (−1H)	2.4		V
I_{DD}	Supply Current (Commercial Temp)	Unloaded outputs at 66.67 MHz, Select inputs at V_{DD}		34	mA
I_{DD}	Supply Current (Industrial Temp)	Unloaded outputs at 100 MHz 66.67 MHz 33MHz Select inputs at V_{DD} or GND, at Room Temp		50 34 19	mA

3. REF input has a threshold voltage of V_{DD}/2.

Table 5. SWITCHING CHARACTERISTICS (Industrial) (Note 4)

Parameter	Description		Test Conditions	Min	Typ	Max	Unit
$1/t_1$	Output Frequency		30 pF load 10 pF load	15 15		100 133	MHz
$1/t_1$	Duty Cycle = $(t_2 / t_1) * 100$	(−1, −1H) (−1H)	Measured at 1.4 V, F_{OUT} = 66.67 MHz < 50 MHz	40 45	50 50	60 55	%
t_3	Output Rise Time	(−1) (−1H)	Measured between 0.8 V and 2.0 V			2.5 1.5	ns
t_4	Output Fall Time	(−1) (−1H)	Measured between 2.0 V and 0.8 V			2.5 1.5	ns
t_5	Output−to−Output Skew		All outputs equally loaded			250	ps
t_6	Delay, REF Rising Edge to CLKOUT Rising Edge		Measured at $V_{DD}/2$		0	±350	ps
t_7	Device−to−Device Skew		Measured at $V_{DD}/2$ on the CLKOUT pins of the device		0	700	ps
t_J	Cycle−to−Cycle Jitter		Measured at 66.67 MHz, loaded outputs			200	ps
t_{LOCK}	PLL Lock Time		Stable power supply, valid clock presented on REF pin			1.0	ms

4. All parameters specified with loaded outputs.

Zero Delay and Skew Control

All outputs should be uniformly loaded to achieve Zero Delay between input and output. Since the CLKOUT pin is the internal feedback to the PLL, its relative loading can adjust the input−output delay.

For applications requiring zero input−output delay, all outputs, including CLKOUT, must be equally loaded. Even if CLKOUT is not used, it must have a capacitive load equal to that on other outputs, for obtaining zero−input−output delay.

SWITCHING WAVEFORMS

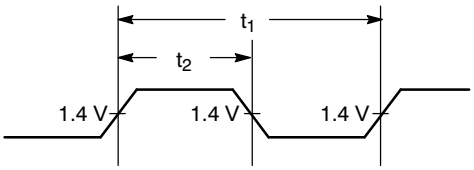


Figure 3. Duty Cycle Timing

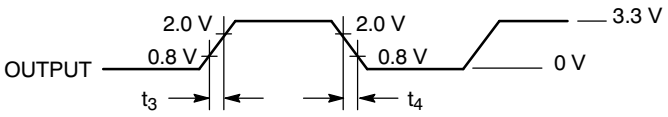


Figure 4. All Outputs Rise/Fall Time

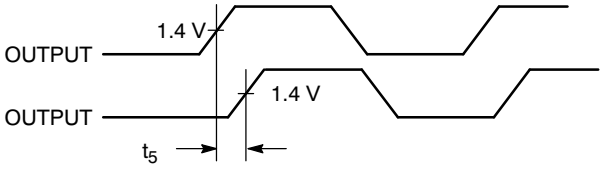


Figure 5. Output − Output Skew

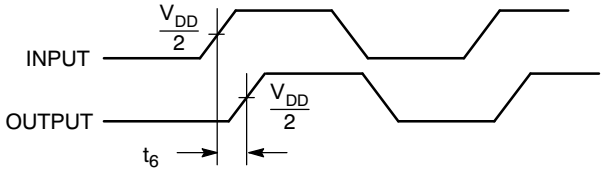


Figure 6. Input − Output Propagation Delay

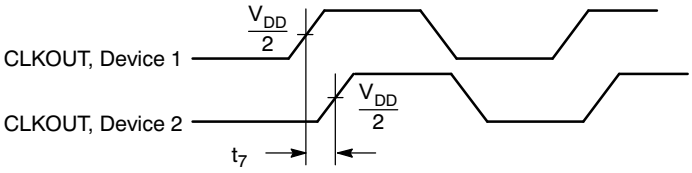


Figure 7. Device − Device Skew

TEST CIRCUITS

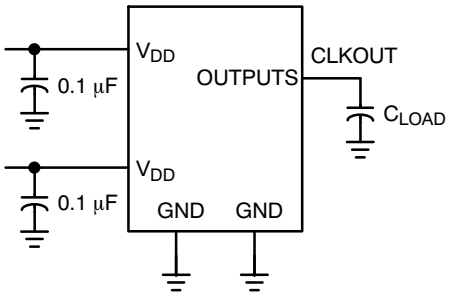


Figure 8. Test Circuit #1

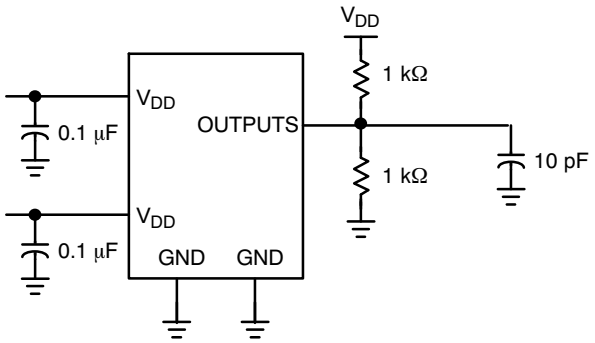


Figure 9. Test Circuit #2
For parameter t_8 (output slew rate) on −1H devices

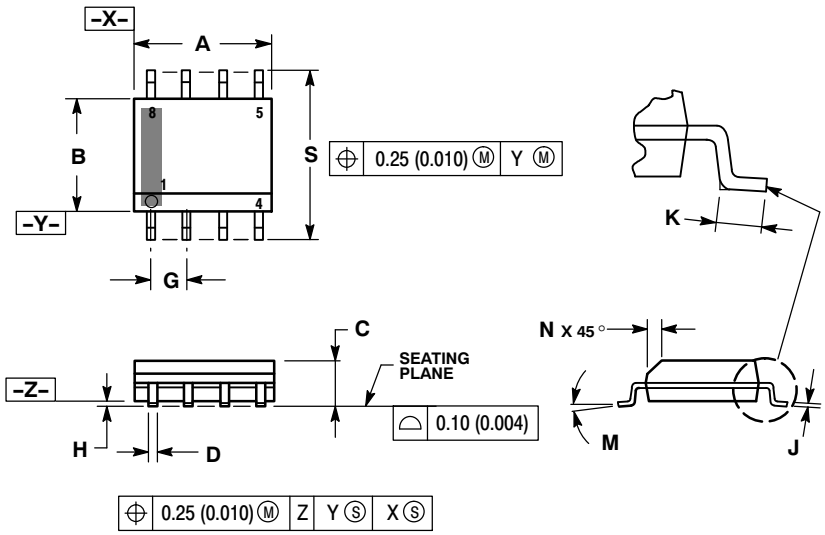
ORDERING INFORMATION

Device	Marking	Operating Range	Package	Shipping†	Availability
NB2305AI1DG	5I1	Industrial	SOIC−8 (Pb−Free)	98 Units / Rail	*Now*
NB2305AI1DR2G	5I1	Industrial	SOIC−8 (Pb−Free)	2500 Tape & Reel	*Now*
NB2305AI1HDG	5I1H	Industrial	SOIC−8 (Pb−Free)	98 Units / Rail	*Now*
NB2305AI1HDR2G	5I1H	Industrial	SOIC−8 (Pb−Free)	2500 Tape & Reel	*Now*
NB2305AI1DTG	5I1	Industrial	TSSOP−8 (Pb−Free)	100 Units / Rail	*Now*
NB2305AI1DTR2G	5I1	Industrial	TSSOP−8 (Pb−Free)	2500 Tape & Reel	*Now*
NB2305AI1HDTG	5IH	Industrial	TSSOP−8 (Pb−Free)	100 Units / Rail	*Now*
NB2305AI1HDTR2G	5IH	Industrial	TSSOP−8 (Pb−Free)	2500 Tape & Reel	*Now*

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

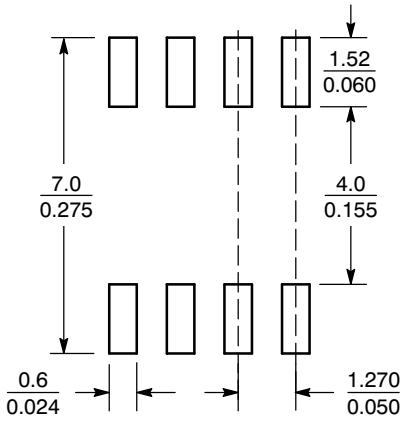
SOIC−8 NB
CASE 751−07
ISSUE AJ



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. 751−01 THRU 751−06 ARE OBSOLETE. NEW STANDARD IS 751−07.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	4.80	5.00	0.189	0.197
B	3.80	4.00	0.150	0.157
C	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27 BSC		0.050 BSC	
H	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

SOLDERING FOOTPRINT*

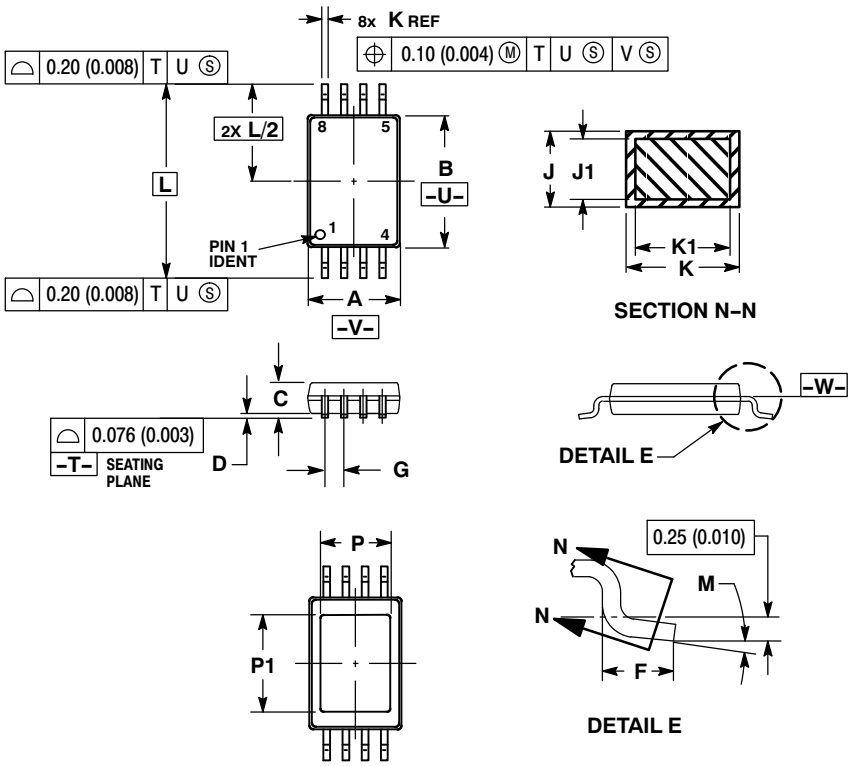


SCALE 6:1 (mm / inches)

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP−8
CASE 948S−01
ISSUE B



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE −W−.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
A	2.90	3.10	0.114	0.122
B	4.30	4.50	0.169	0.177
C	---	1.10	---	0.043
D	0.05	0.15	0.002	0.006
F	0.50	0.70	0.020	0.028
G	0.65 BSC		0.026 BSC	
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
M	0 °	8 °	0 °	8 °
P	---	2.20	---	0.087
P1	---	3.20	---	0.126

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
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